Atomic Scale Processing Mini-Symposium
Room 316 - Session AP1+EL+MS+PS+TF-TuA

Advanced Atomic Scale Processing through Modeling and Simulation

Moderators: Prof. Dr. David Graves, Princeton University, **Prof. Dr. Satoshi Hamaguchi**, Osaka University, Japan

2:15pm **AP1+EL+MS+PS+TF-TuA-1 Design and performance of AI agents interfacing with atomic layer deposition tools**, ***Angel Yanguas-Gil,*** Argonne National Laboratory **INVITED**

In recent years there has been an increased interest in exploring the integration of generative AI in combination with experimental tools to create multipurpose autonomous systems that can solve complex research problems. This vision relies on AI agents based on LLMs that can autonomously interact with experiments to solve multiple tasks (e.g. "Grow 20 nm of tin oxide" or "selectively grow 10 nm of Cu on Co but not on silicon oxide"). However, in order to be useful, these systems have to be compatible with state of the art manufacturing tools and they have to perform reliably well in a broad enough set of materials synthesis tasks.

In this presentation, I will focus on these two aspects in the context of atomic scale processing. First, I will describe how we have augmented an existing ALD tool so that it can be integrated with generative AI models. Our approach relies on defining a Python interface and API that abstract all the specific details of the hardware from the AI agent, while making it compatible with standard approaches for tool use with LLMs. I will also describe how we have implemented AI agents that can communicate with this ALD tool as well as with existing data, such as data logs and background data on ALD and area selective deposition.

In the second part of the presentation, I will introduce a general methodology to evaluate the performance of AI agents on atomic scale processing tasks. We have applied it to evaluate the performance of state of the art models in instruction, process discovery, and materials discovery challenges in the context of atomic scale processing, primarily ALD and selective growth. In all these cases the output of the challenge is a specific instruction to run one or more processes in an ALD tool. Our results show that state of the art models excel at instruction tasks, but they struggle on process and materials discovery tasks where they involve processes and materials that are underrepresented in the literature, pointing to potential limitations and areas of improvement for for future AI models specialized in materials synthesis and atomic scale processing.

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2:45pm **AP1+EL+MS+PS+TF-TuA-3 A Multiscale Framework for ALD/ALE Process and Precursor Development Using Neural-Network-Potential Atomistic Simulations and COSMO-SAC Thermodynamic Modeling**, ***Yukihiro Shimogaki,*** The University of Tokyo, Japan

Atomic layer deposition (ALD) is indispensable for gate-all-around transistors, high-aspect-ratio DRAM capacitors, and 3D NAND, where conformality and precise thickness control are both required. Atomic layer etching (ALE), the reverse of ALD, matters for low-damage, selective integration, while area-selective deposition (ASD) is attractive but suffers "selectivity loss": unwanted nuclei form on non-growth areas and degrade selectivity over time. We present a multiscale framework coupling COSMO-SAC thermodynamic modeling for precursor down-selection with neural-network-potential (NNP) atomistic simulations for reaction-mechanism analysis; an integrated ALD+ALE scheme designed within it enables highly selective, robust ASD.

An ideal precursor reaches saturation adsorption and is delivered stably; a vapor pressure >=100 Pa below 100 C, preferably ~1000 Pa, broadens the process window. Conventional COSMO-SAC is often inaccurate for metal-containing organometallics. By tuning dispersion-related parameters we obtained good agreement between predicted and measured vapor pressures, enabling efficient down-selection. For Co precursors the framework predicted a high vapor pressure for CpCoCOTFE; the synthesized compound showed ~1060 Pa at 85 C. The same volatility prediction directly guides ALE, where formation and removal of volatile products are central.

Surface-reaction analysis has long been limited by the cost of reaction-path and vibrational searches. NNP-based simulations (e.g., Matlantis) now provide near-DFT accuracy at large scale, making ALD/ALE surface mechanisms tractable. For the Co precursor, NNP indicated that controlling surface hydrogen coverage prior to dosing suppresses carbon incorporation from side reactions; this was confirmed experimentally, showing precursor design (vapor pressure) and reaction design (surface state) must be co-optimized.

For ASD with CCTBA, NNP molecular dynamics showed facile reaction on Cu but low reactivity on SiO_2, and selective growth on Cu was experimentally confirmed. Residual Co nuclei on SiO_2 degrade selectivity; we designed an ALE path in which Co is chlorinated by SO_2Cl_2 and reacts with Hfac to form volatile products whose volatility is supported by COSMO-SAC. The resulting ALD (growth) + ALE (nuclei removal) scheme restores robust selectivity. Finally, sub-monolayer growth per cycle (~0.1 ML) is rationalized by steric hindrance, and NNP-MD with kinetic Monte Carlo captures these collective adsorption dynamics. This COSMO-SAC + NNP framework offers a unified route to co-develop ALD/ALE processes (Atomic Layer Process, ALP) and precursors and to overcome ASD selectivity loss.

3:00pm **AP1+EL+MS+PS+TF-TuA-4 Re-designing ALD Experiments for AI-ready Data: The IGZO Case Study**, ***Eleni Poupaki,*** *Cas Visser, Freek Klabbers, Adrie Mackus, Erwin Kessels,* Eindhoven University of Technology, The Netherlands

The AtomicLimits ALD database [1] is a community-driven repository of ALD processes from the literature. The next step is to populate it with more data suitable for artificial intelligence (AI) and machine learning (ML) models. [2] Recent efforts have used large language models for structured data extraction from publications. [3] However, literature data remains fundamentally limited for data-driven modeling: it is incomplete, often missing key process parameters, biased toward successful experiments, and inconsistently reported. ML can accelerate ALD development by predicting film properties, guiding experiment design, and identifying optimal recipes. Unlocking this potential requires not only more data, but experiments designed to produce data suitable for ML. We address this challenge using ALD of InGaZnO (IGZO) as a case study. IGZO is a quaternary oxide semiconductor that has emerged as an alternative to crystalline silicon channels, used in displays and increasingly explored for DRAM. Amorphous IGZO exhibits high electron mobility, ultralow leakage, and a low thermal budget. [4,5] ALD is well-suited for IGZO, due to its sequential, self-limiting surface reactions, enabling precise control of thickness and composition. [6] For multicomponent materials like IGZO, composition is controlled via the supercycle approach, with subcycles of In_2O_3, Ga_2O_3, and ZnO. Their relative ratios and sequence strongly influence the resulting film properties [7], creating a vast, interdependent parameter space. In this work, we develop a protocol for generating AI-ready ALD experimental data, demonstrated on IGZO. The protocol proceeds stepwise from binary to ternary to quaternary processes, with explicit criteria at each stage: binary processes are characterized for saturation and nucleation, and the ternaries (GaZnO, InZnO, InGaO) are screened to identify supercycle criteria. Using these findings, we explore the supercycle parameter space, focusing on cycle ratio and mixing, with consistent characterization. We discuss preliminary trends in crystallinity and electrical properties across the explored space, contrasting with conventional optimization-driven experimentation. Finally, we outline how the resulting datasets enable ML-guided exploration of the IGZO supercycle space, paving the way toward AI-assisted ALD process optimization and a richer experimental foundation for community resources such as AtomicLimits.

[1] 10.6100/alddatabase

[2] Westermayr et al., Chem. Mater. 2026.

[3] Saddrudin, Poupaki et al., JVSTA 2026.

[4] Song et al., Nat. Electron. 2025.

[5] Okajima et al., IEDM 2025.

[6] Sheng et al., ACS AMI 2019.

[7] Oh et al., Ceram. Int. 2025.

3:15pm **AP1+EL+MS+PS+TF-TuA-5 Atomistic Modeling of Atomic Layer Etching and Deposition: HF/SiO2 ALE and TMA/Al2O3 ALD**, ***Fedor Goumans,*** Software for Chemistry & Materials, Netherlands

Atomic layer processes rely on surface reactions that are sequential, self-limiting, and highly sensitive to local chemical structure. Understanding these reactions at the atomistic level is essential for improving atomic layer deposition, atomic layer etching, and area-selective processing, but many key reaction steps occur at buried, transient, or chemically heterogeneous interfaces that are difficult to characterize directly. In this presentation, we

discuss how reactive atomistic simulations can support the interpretation and design of atomic layer processes, with examples from HF-based SiO_2 etching and TMA/Al_2O_3 deposition.

Reactive force fields and machine-learned interatomic potentials provide complementary routes for exploring surface chemistry over length and time scales beyond conventional first-principles molecular dynamics. Using these approaches, one can follow bond breaking and formation, surface hydroxylation, ligand exchange, fluorination, densification, and volatile product formation under process-relevant conditions. For SiO_2 etching, simulations can help identify how HF exposure modifies hydroxylated and strained oxide surfaces, how local bonding environments influence fluorination and material removal, and which surface motifs may control etch initiation. For Al_2O_3 deposition, simulations of TMA reactions with hydroxylated alumina surfaces can reveal the molecular origin of saturation behavior, steric effects, methane elimination, and the evolution of reactive surface sites across ALD cycles.

The broader goal is to connect the relevant calculated parameters such as sticking rate, thermal accommodation coefficients, and atomistic reaction mechanisms with experimentally observable trends in growth, etch rate, selectivity, and film quality. We highlight practical considerations for building reliable reactive models, including training data selection, validation against quantum chemical calculations, and the use of accelerated workflows. These examples illustrate how atomistic modeling can complement experiments by exposing reaction pathways, identifying limiting surface structures, and guiding the development of more predictive models for ALD and ALE process optimization.

4:00pm **AP1+EL+MS+PS+TF-TuA-8 Characterizing Directionality, Energy and Spatial Uniformity of Plasma Generated Neutral Beams for Low-Damage Material Processing***, **Gonçalo A. Cardoso**, Mark J. Kushner,* University of Michigan, Ann Arbor

Ion bombardment onto biased wafers during plasma etching can result in charge buildup within features that can deflect incoming ion trajectories, resulting in feature defects such as bowing or notching, or lead to device damage. UV photons emitted from the plasma might also cause surface defects such as dangling bonds [1]. These issues are exacerbated as device dimensions are scaled down, due to larger electric fields for a given charging potential and increased surface-to-volume ratio. This is particularly the case for the fabrication of 2-dimensional materials consisting of nearly monolayer thickness. Energetic neutral beams have been proposed as an alternative, low-damage and charge-free technique for etching and deposition, and particularly so for 2D materials. Such beams can be produced through ion acceleration and subsequent neutralization, either through charge-exchange collisions (volume neutralization) or by reflection from surfaces (surface neutralization) [2, 3]. The primary technical challenges for neutral beam sources involve optimization of directionality, energy and spatial uniformity of the energetic neutral fluxes striking the substrate.

In this paper, we discuss the results of a computational investigation of a neutral beam source consisting of an inductively coupled plasma separated from the wafer by a radio frequency (RF) biased grid powered at 10 MHz. Typical conditions for this source are pressures of tens of mTorr, gas mixtures containing Ar, O_2 and Cl_2 and biases on the grid of hundreds of volts. This source has been simulated using the Hybrid Plasma Equipment Model (HPEM).The Plasma Chemistry Monte Carlo Module (PCMCM) in the HPEM tracks the motion of ions (and neutrals) as they are accelerated by electric fields, collide with background gas particles and neutralize by reflecting from the grid. The PCMCM records the resulting neutral energy and angular distributions (NEADs) at the wafer. This work investigates the characteristics of these NEADs and how they are influenced by grid surface roughness (non-specular scattering), inelastic scattering from the grid, gas-phase charge-exchange reactions and pressure gradients across the grid.

This work was supported by the US Department of Energy, Office of Science, Fusion Energy Sciences (FES) and Basic Energy Sciences (BES) as part of the Extreme Lithography & Materials Innovation Center (ELMIC), a Microelectronics Science Research Center (MSRC), through the Plasma-enabled 2D Materials project (DEAC02-09CH11466); and by FES (SC-00274510).

4:15pm **AP1+EL+MS+PS+TF-TuA-9 Plasma Etching of Diamond: Molecular Dynamics Studies and Comparison to Experiments***, **Louis Hoffenberg**,* Princeton University*; Justin Boles,* University of Houston*; Jack Draney,* Princeton University*; Igor Kaganovich,* Princeton Plasma Physics Laboratory*; Vincent Donnelly,* University of Houston*; David Graves,* Princeton University

Nitrogen-vacancy (NV) centers in diamond are promising for multiple applications in quantum information processing and sensing, including in the fields of high-power/high-frequency electronics, quantum computing, and quantum sensing.[1] Diamond NV centers near surfaces can locally detect and measure physical quantities such as magnetic and electric fields with unprecedented sensitivity. However, these devices are currently limited by near-surface (<10 nm) defects that compromise charge stability and spin coherence.[2] Plasma etching of diamond has been widely employed to process and pattern diamond, but there is limited understanding of the mechanisms of plasma etching. In this work, classical molecular dynamics (MD) simulations are used to simulate O_2/Ar plasma etching of diamond, with comparisons to experiment. We explore both conventional reactive ion etching (RIE) and atomic layer etching (ALE) conditions. The experimentally validated MD simulations are used to identify fundamental etch mechanisms. Based on the MD simulations, we propose a parameterized reduced order model of diamond plasma etching that relates etch yield to ion flux, ion energy, and ion composition, as well as neutral O• radical to ion flux ratio.

References:

[1] Janitz et al. "Diamond surface engineering for molecular sensing with nitrogen-vacancy centers." J. Mat. Chem. C 10.37 (2022): 13533-13569.

[2] Sangtawesin et al. "Origins of diamond surface noise probed by correlating single-spin measurements with surface spectroscopy." Phys. Rev. X 9.3 (2019): 031052.

4:30pm **AP1+EL+MS+PS+TF-TuA-10 Predictive Screening of Sustainable Etchants via DFT Thermodynamics, Machine-Learned Vapour Pressures, and Infrared Spectra***, **Christopher Pashartis**, Philippe Bezard, Konstantina Philippidou, Geoffrey Pourtois,* IMEC Belgium*; Hideharu Shimizu, Yoshiki Nakoyama,* NSC, Belgium

Fluorinated etchants are heavily used in semiconductor processes for their high etch rates and material selectivity. Typical etchants such as CF_4 and c-C_4F_8 have global-warming potentials in the range of 7,400-13,900 over 100 years and atmospheric lifetimes exceeding hundreds of years, raising concern about the by-products of such processes. While abatement downstream is standard practice, it runs continuously and is never fully effective. Therefore, a more impactful path to reducing the climate footprint of fabrication is to identify replacement etchants that are intrinsically more sustainable while remaining competitive in performance.

Experimentally screening new etchants includes sourcing gases, fine-tuning reactor conditions, characterising effluent; it can be very slow and time consuming. We present a predictive screening workflow built on Density Functional Theory (DFT) rather than specialised plasma simulations: DFT-derived Gibbs free energies are used to solve the closed-system equilibrium for each etchant-substrate pair, giving both the predicted etch capability and the by-product distribution as a function of temperature, pressure, and stoichiometry. To translate predicted species into global warming potential, we couple this with two further ingredients: a graph neural network trained on open-source vapourpressure data to determine which by-products are most likely to be gaseous, and DFT-computed infrared spectra to estimate their radiative efficiency. We will present results aggregated across more than ten candidate etchants and three substrates (Si, SiO_2, Si_3N_4), demonstrating how the combined thermodynamics-volatility-impact screen can rank chemistries by their projected greenhousegas burden.

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